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Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023 Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number						
		BAT854W-Q						
		Part Description						
		Nexperia DHAM Schottky						
		SMD package						
		Test Conditions Duration # Lots # Quantity						
	TEST				,	# Rejects		
	Pre- and Post-Stress							
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
		1ESD22-A113			un purco	bee below		
		Bake Tamb = $125 ^{\circ}\text{C}$	24 hours					
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours					
# A1	Preconditioning	Reflow soldering	3 cycles	1514	64430	0		
	5	MIL-STD-750-1	•					
	HTRB	M1038 Method A						
		Tj = Tjmax, Vr = 100% of max. datasheet						
# B1	Bias	reverse voltage ^[1]	1000 hours	206	9320	0		
	тс	JESD22-A104						
# A4	Temperature Cycling	-65 °C to Timax, not to exceed 150°C	1000 cycles	311	14080	0		
	, , ,							
	UHAST	JESD22-A118						
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %						
		JESD22-A102	96 hours	311	14080	0		
	AC	Tamb = $121 ^{\circ}C$, RH = $100 ^{\circ}M$						
# A3 alt	Autoclave	Pressure = $205 \text{ kPa} (29.7 \text{ psia})$						
, no are								
	H3TRB	JESD22-A101						
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of						
# A2 alt	Temperature Reverse Bias		1000 hours	311	14080	0		
# 712 UIC	- p	MIL-STD-750 Method 1037	10000	011	1.000	5		
	IOL	ton = toff, devices powered to insure ΔT_j =						
# A5	Intermittent Operating Life		1000 hours	312	14120	0		
# A3			2000 110010	512	- 1120	-		
	RSH	JESD22-A111						
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	269	8070	0		
	SD	200 0-0 0	10.5	205	0070	0		
# C10	Solderability	J-STD-002		222	6660	0		
	,	des have to be considered (thermal runaway).		~~~	0000	0		

The physical limitations of Schottky diodes have to be considered (thermal runaway).
The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	9320	0	0,46	2,19E+09

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